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INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION <small>(Use several sheets if necessary)</small>		Applicant: William C. Phillips; Alex C. Toy; Charles R. Lewis, Jr.; Mark E. Schommer; John W. Forsberg; David P. Olson	
		Filing Date: October 24, 2003	Group Art Unit: 3762
		Examiner Name: Tammie K. Heller	

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EXAMINER	Date Considered
<i>Tammie Heller</i>	<i>Jan-24 2006</i>

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.